Compliant with IEC 62474/ D9.00 Compliant to IEC 61249-2-21:2003

MICROCHIP  Semiconductor Device Type: NQA 20 VQFN 4x3x0.9mm NiPdAu			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)				J-STD-609A Product Marking and/or Pkg. Labeling e4
Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm	15.12	(mg) Total	Mold Compound	% ot Total Weight	48.15
Silica, fused	60676-86-0	Mold Compound	43.335	13.607	433,350		Silica, fused	60676-86-0	90.00	
Epoxy Resin	Trade Secret	Mold Compound	2.335	0.733	23,353		Epoxy Resin	Trade Secret	4.85	
Phenolic Resin	Trade Secret	Mold Compound	2.335	0.733	23,353		Phenolic Resin	Trade Secret	4.85	
Carbon Black	1333-86-4	Mold Compound	0.144	0.045	1,445		Carbon Black	1333-86-4	0.30	
Copper	7440-50-8	Lead Frame	41.419	13.005	414,187			Total	100.00	
Iron	7439-89-6	Lead Frame	0.062	0.020	623	13.03	(mg) Total	Lead Frame	% of Total Weight	41.51
Phosphorous	7723-14-0	Lead Frame	0.017	0.005	166		Copper	7440-50-8	99.78	
Zinc (Metal)	7440-66-6	Lead Frame	0.012	0.004	125		Iron	7439-89-6	0.15	
Silver	7440-22-4	Die Attach	0.909	0.285	9,086		Phosphorous	7723-14-0	0.04	
Epoxy resin	68475-94-5	Die Attach	0.236	0.074	2,360		Zinc (Metal)	7440-66-6	0.03	
Copper(II) oxide	1317-38-0	Die Attach	0.035	0.011	354			Total	100.00	
Silicon	7440-21-3	Chip (Die)	5.150	1.617	51,500	0.37	(mg) Total	Die Attach	% of Total Weight	1.18
Gold	7440-57-5	Wire Bond	2.880	0.904	28.800	0.01	Silver	7440-22-4	77.00	1.10
Nickel	7440-02-0	Plating on external leads (pins)	1.044	0.328	10.437		Epoxy resin	68475-94-5	20.00	
Palladium	7440-02-0	Plating on external leads (pins)	0.084	0.026	836		Copper(II) oxide	1317-38-0	3.00	
i alladidili					27		Copper(II) oxide	Total	100.00	
Cold	7440 57 5									
Gold	7440-57-5	Plating on external leads (pins)	0.003	0.001		4.00	Total (mm)			E 4E
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